

SOLIDWORKS GENERATED DRAWING, DO NOT CHANGE BY HAND

NOTES:

1. ELECTRICAL CHARACTERISTICS:

- 1.1. CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
- 1.2. VOLTAGE RATING: 25V AC.
- 1.3. INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
- 1.4. DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz, FOR 1 MINUTE.
- 1.5. CONTACT RESISTANCE: 50 MILLIOHMS MAX. PER PIN INITIAL
60 MILLIOHMS MAX. PER PIN AFTER FULL ENVIRONMENTAL TESTING.

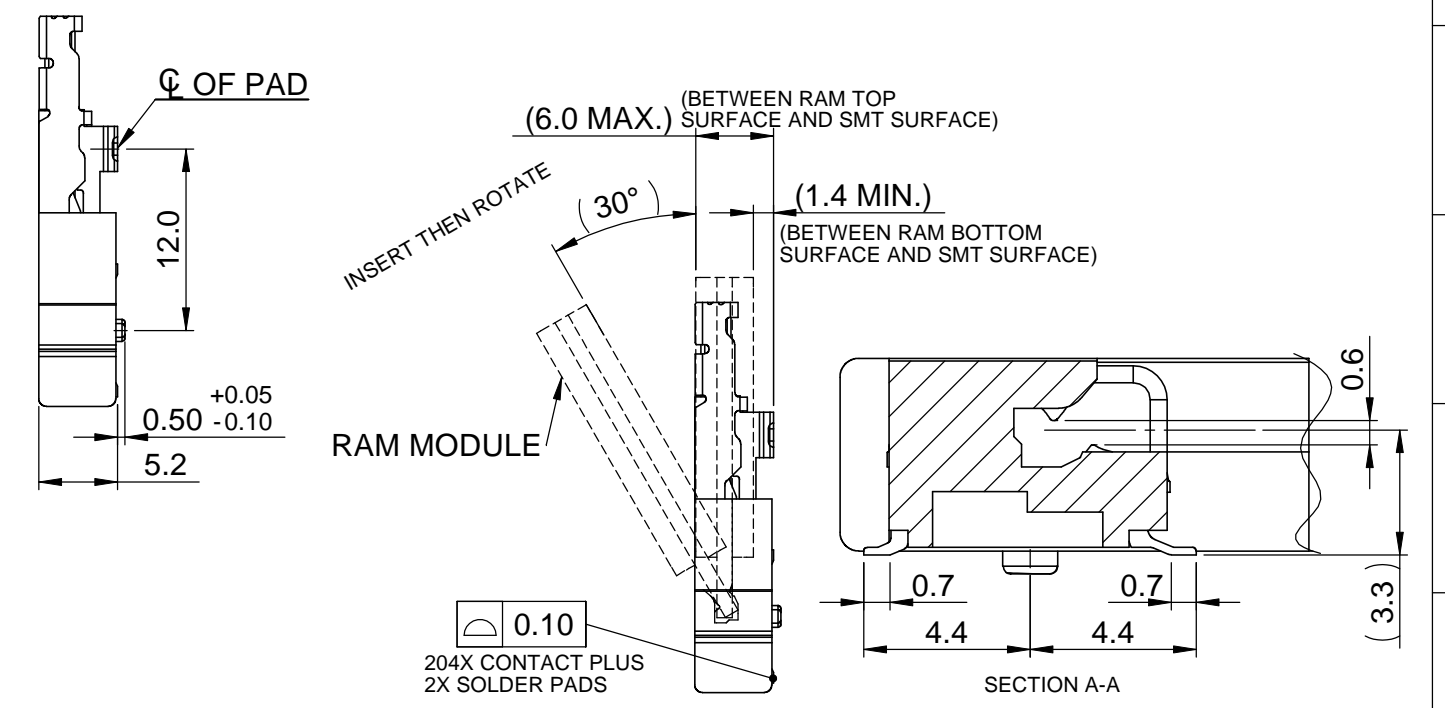
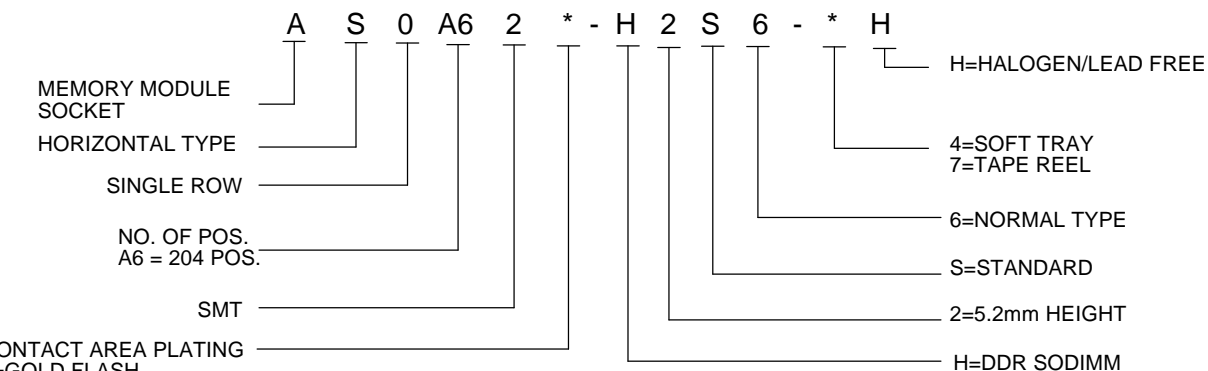
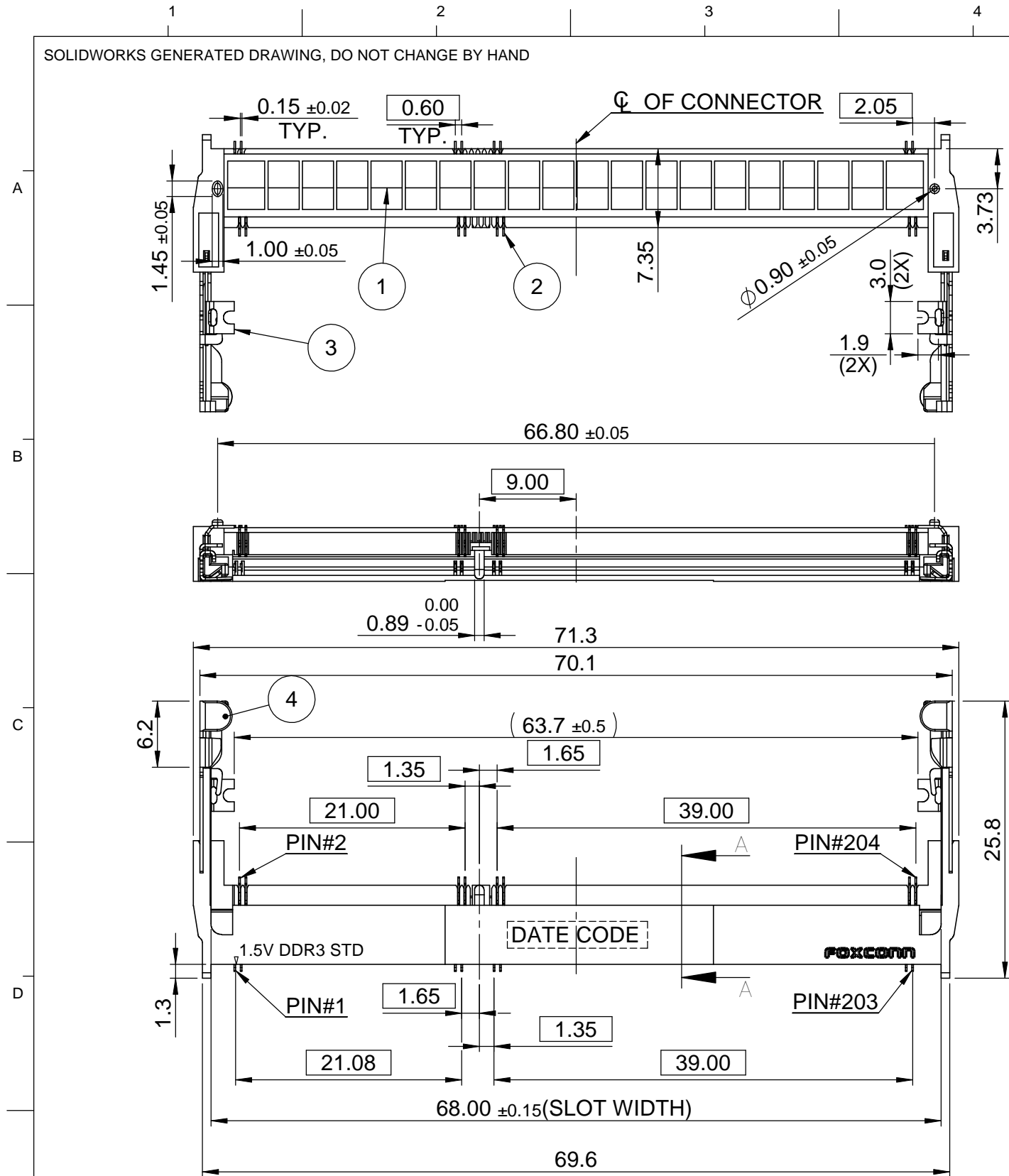
2. MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.

3. OPERATION TEMPERATURE: -55 °C TO +85 °C.

4. RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260 °C 10~20S.

5. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.

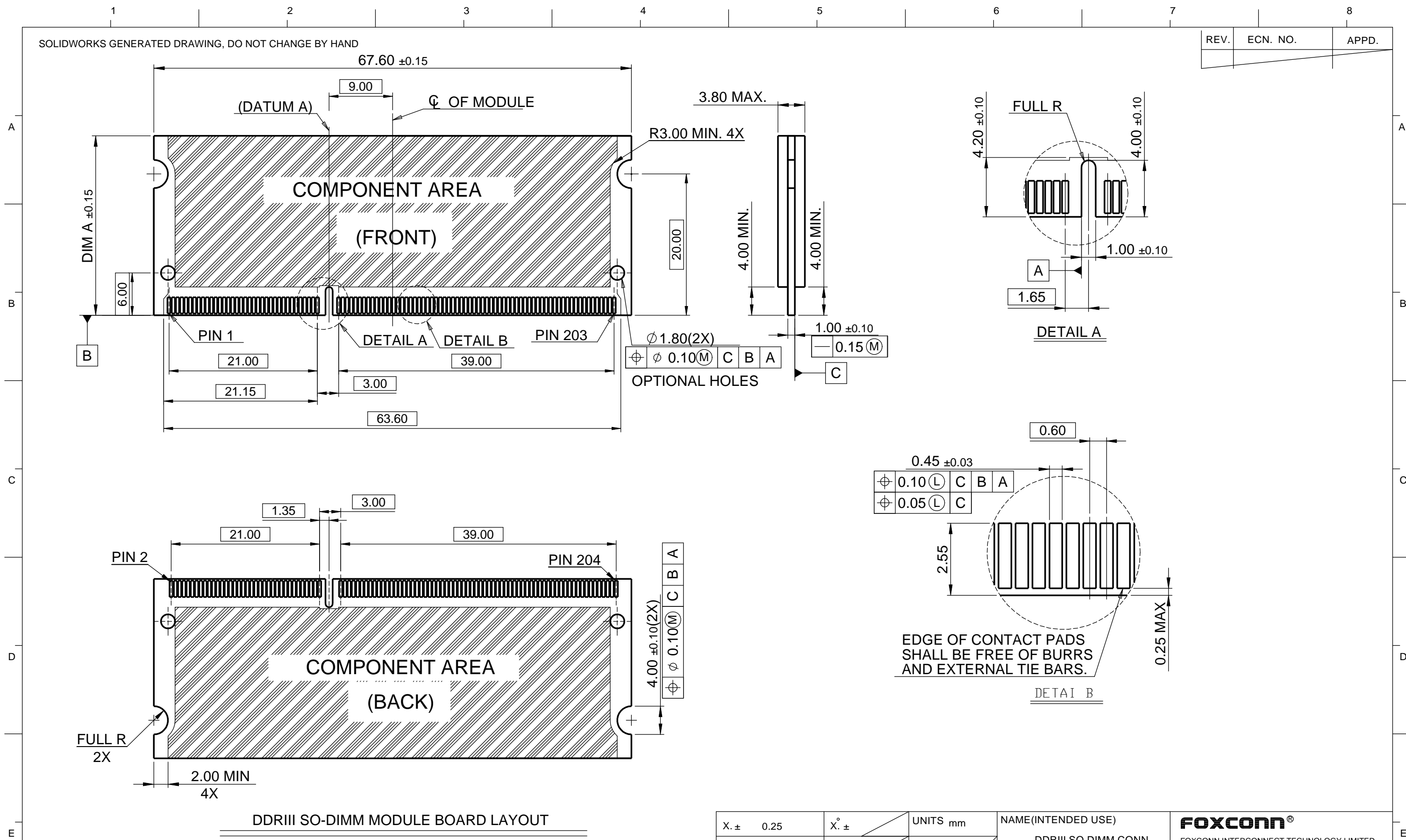
REV.	ECN. NO.	APPD.
A	BC-12-0044551	Aaron Mao
B	BC-12-0058892	Bruce Wu
C	BC-13-0039179	C.S Li
D	BC-13-0081932	C.S Li
E	BC-14-0008650	C.S Li



ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT
4	METAL SPRING	2	STAINLESS STEEL	ULTRASONIC CLEANING
3	METAL PAD	2	STAINLESS STEEL	10u" NICKEL UNDER PLATING 100u" MATTE TIN PLATING OVER SOLDER PAD AREA
2	CONTACT	204	COPPER ALLOY	50u" NICKEL UNDER PLATING GOLD FLASH OR 5u" OR 10u" OR 15u" OR 30u" GOLD PLATING AT CONTACT AREA; GOLD FLASH PLATING AT TAIL
1	HOUSING	1	THERMOPLASTIC	UL94V-0, HALOGEN FREE, IVORY COLOR

X. ± 0.30	X. °	UNITS mm	NAME (INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.25	.X °		DDR III SO DIMM CONN.	
.XX ± 0.15	.XX °	MAT'L	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX °		AS0A62*-H2S6*-H	
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			QTY	DWG NO.: 317-0000-2138
			APPD: C.S Li	SCALE SHEET REV. N/A 1/5 E
			CHKD: Alex Wang	
			DRAW: Gary Xu 2014/2/26	

REV.	ECN. NO.	APPD.



OPTIONAL HOLES

⊕	⊕ 0.10 (M)	C	B	A
⊕	⊕ 0.15 (M)	C		

⊕	⊕ 0.10 (L)	C	B	A
⊕	⊕ 0.05 (L)	C		

DDR III SO-DIMM MODULE BOARD LAYOUT

SDRAM VARIATIONS	DIM A
TYPE 1	25.40
TYPE 2	31.75
TYPE 3	30.00

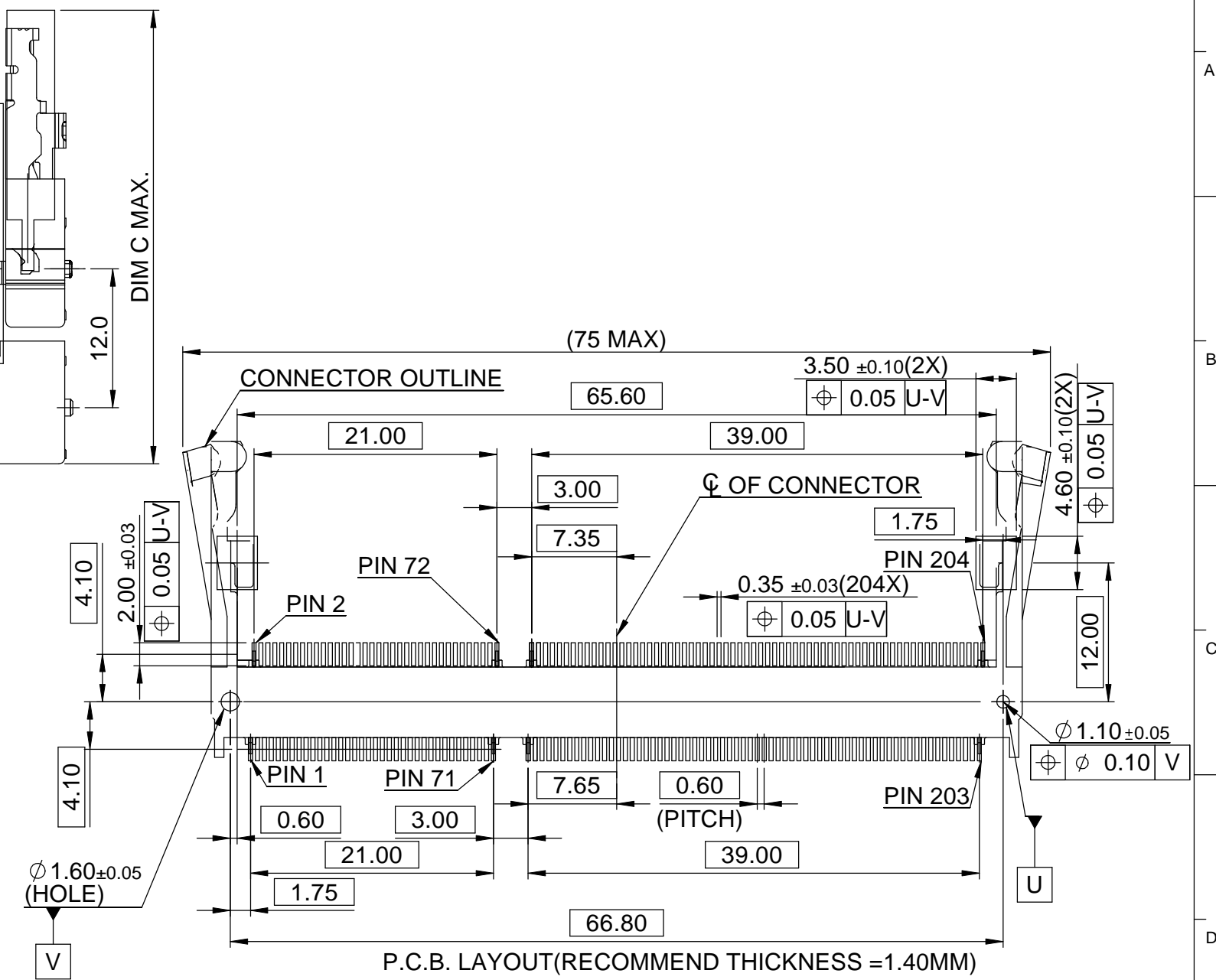
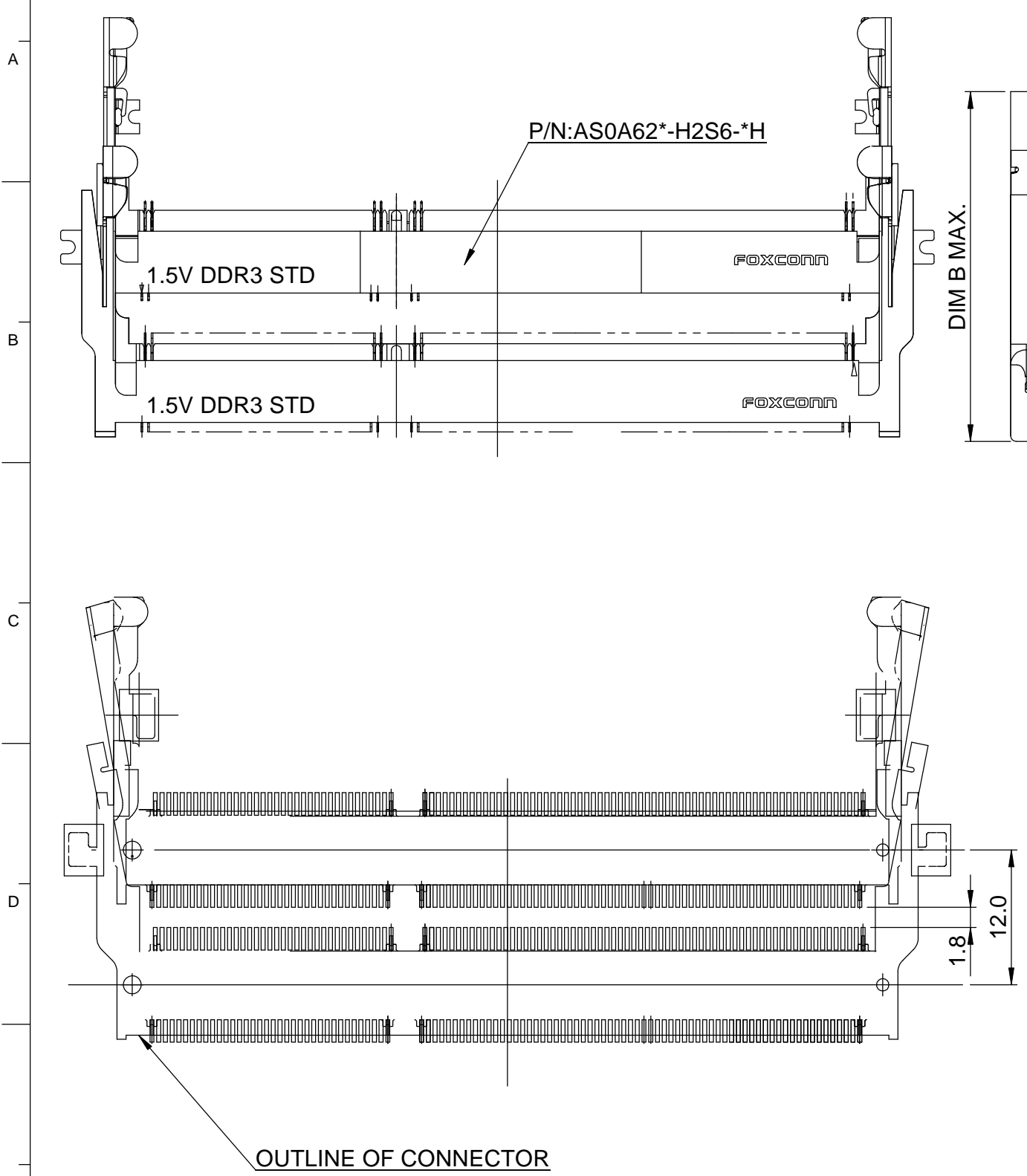
X. ± 0.25	X. °	UNITS mm
.X ± 0.10	.X °	MAT'L
.XX ± 0.05	.XX °	FINISH
.XXX ±	.XXX °	QTY

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NAME (INTENDED USE)	DDR III SO DIMM CONN.	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
PART NO. (INTENDED USE)	AS0A62*-H2S6-*H	
APPD:	C.S Li	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
CHKD:	Alex Wang	TITLE: CUSTOMER DRAWING
DRAW:	Gary Xu 2014/2/26	DWG NO.: 317-0000-2138
		SCALE SHEET REV. N/A 2/5 E

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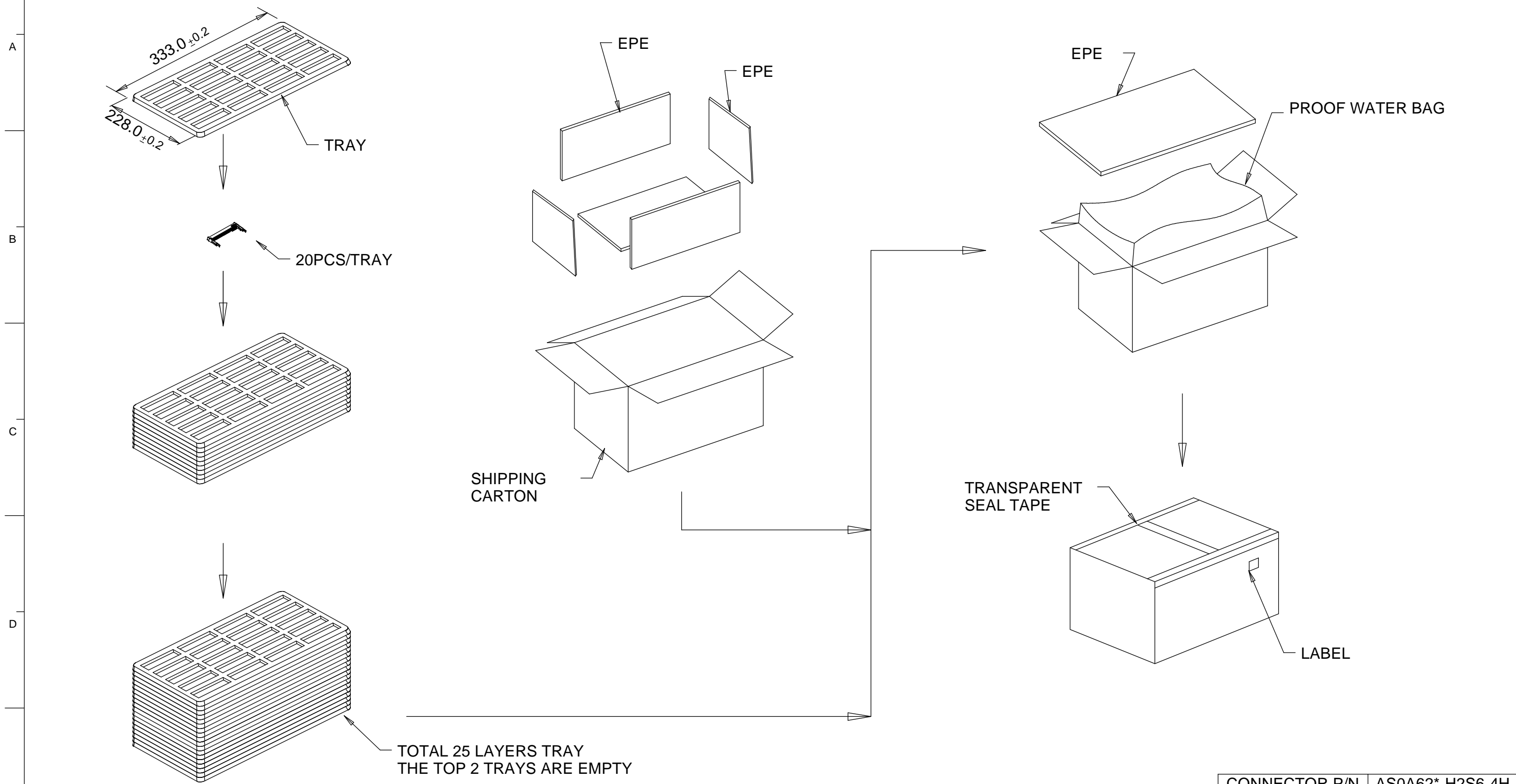


SDRAM VARIATIONS	DIM B	DIM C
TYPE 1	30.4	42.4
TYPE 2	36.7	48.7
TYPE 3	35.0	47.0

X. ± 0.25	X. °	UNITS mm	NAME (INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.15	.X °		DDRIII SO DIMM CONN.	
.XX ± 0.05	.XX °	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX °		AS0A62*-H2S6-*H	TITLE: CUSTOMER DRAWING
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			CHKD: Alex Wang	SCALE SHEET REV.
			DRAW: Gary Xu 2014/2/26	N/A 3/5 E

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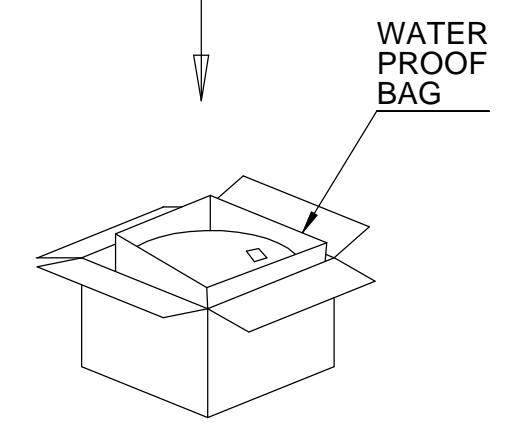
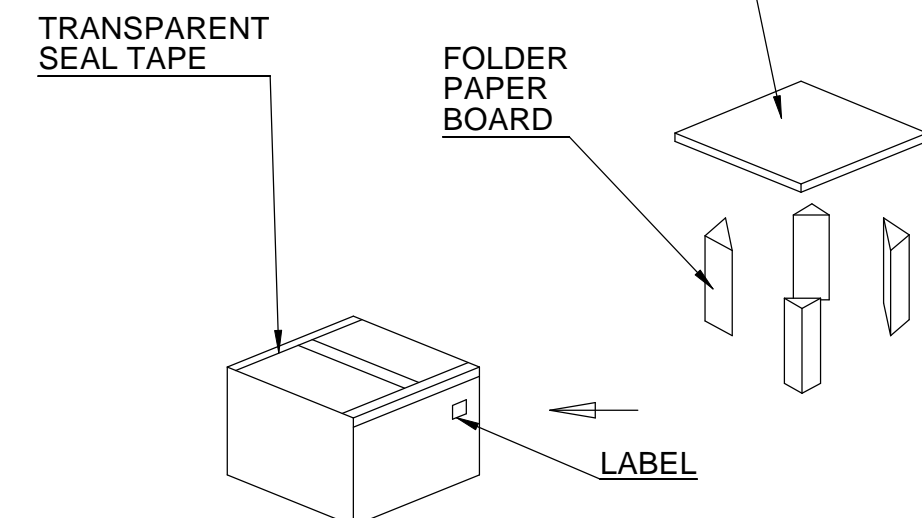
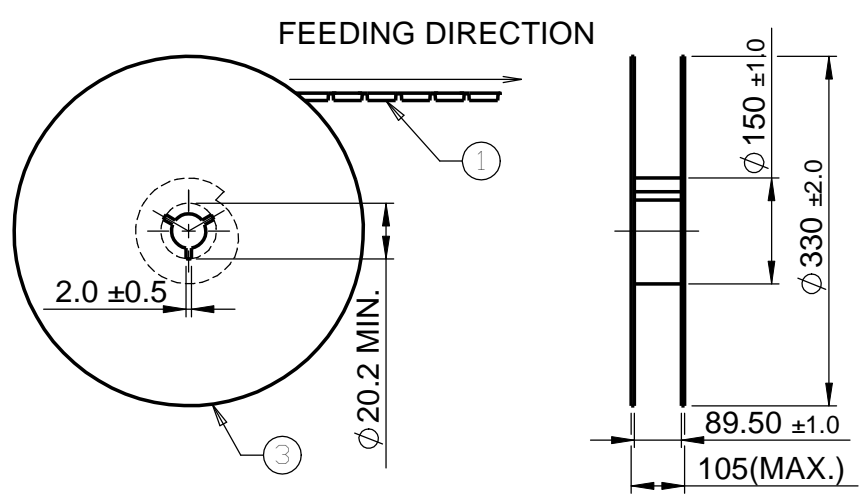
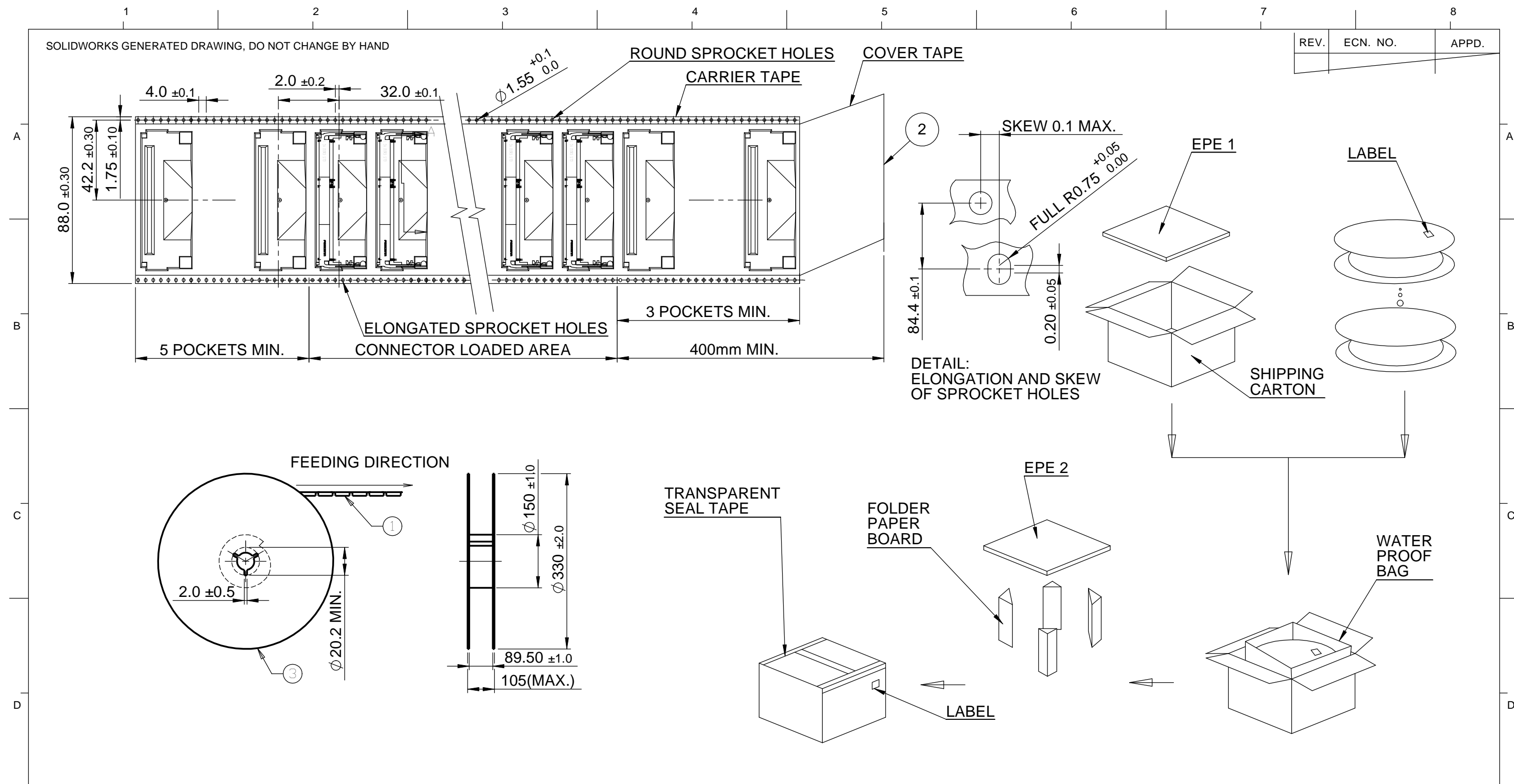
NOTES:
1. PACKING CAPACITY : 20 PCS/TRAY, 23 TRAYS/BOX,
TOTAL 460 PCS/BOX.

CONNECTOR P/N AS0A62*-H2S6-4H

X. ±	X. ° ±	UNITS mm	NAME (INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ±	.X ° ±	MAT'L	DDRIII SO DIMM CONN.	
.XX ±	.XX ° ±	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX ° ±		AS0A62*-H2S6-*H	TITLE: CUSTOMER DRAWING
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			CHKD: Alex Wang	
			DRAW: Gary Xu 2014/2/26	

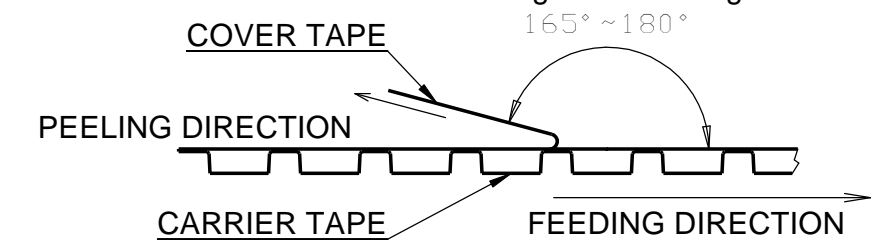
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REV.	ECN. NO.	APPD.



NOTES:

- 1. 10 POCKETS HOLE PITCH CUMULATIVE TOLERANCE ±0.20mm.
- 2. COVER TAPE PEELING STRENGTH : 0.01 kgf MIN. 0.15 kgf MAX. AT 300mm/min.



3. PACKING CAPACITY : 250 PCS/REEL, 3 REELS/BOX, TOTAL 750 PCS/BOX.

3	REEL	POLYSTYRENE
2	COVER TAPE	POLYESTER
1	CARRIER TAPE	POLYSTYRENE
ITEM	DESCRIPTION	MATERIAL

X. ± 1.5	X. °	UNITS mm	NAME (INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 1.0	.X °	MAT'L	DDRIII SO DIMM CONN.	
.XX ± 0.2	.XX °	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX °		AS0A62*-H2S6-*H	TITLE: CUSTOMER DRAWING
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			CHKD: Alex Wang	SCALE SHEET REV. N/A 5/5 E
			DRAW: Gary Xu 2014/2/26	

CONNECTOR P/N AS0A62*-H2S6-7H